CLAIMS

[1] A cover film comprising at least, in order, a substrate layer (A), an intermediate layer (B), a peel layer (C) and a heat seal layer (D), wherein

the peel layer (C) comprises a resin composition comprising a styrenic resin composition (a) having a styrene-diene block copolymer as a main component, and an ethylene-α-olefin random copolymer (b), the ethylene-α-olefin random copolymer occupying 20 to 50 mass% of the peel layer, and having a Vicat softening temperature of 55 to 80 °C; and

the heat seal layer (D) comprising an acrylic resin with a glass transition temperature of 55 to 80 °C.

[2] The cover film according to claim 1, wherein the thickness of the substrate layer (A) after drying is 12 to 20 μm, the thickness of the intermediate layer (B) after drying is 10 to 40 μm, the thickness of the peel layer (C) after drying is 5 to 20 μm, and the total thickness of the cover film after drying is 45 to 65 μm.

[3] The cover film according to either one of claims 1 and 2, wherein the heat seal layer (D) comprises 100 to 700 parts by mass of conductive microparticles of one of tin oxide, zinc oxide and zinc antimonate having a mass-average particle size of 1.0 μm or less, with respect to 100 parts by mass of the resin constituting the heat seal layer (D).

[4] The cover film according to any one of claims 1 to 3, wherein the heat seal layer (D) comprises 40 to 100 parts by mass of a cationic polymer-type anti-static agent having a quaternary ammonium salt on a side chain, with respect to 100 parts by mass of the resin constituting the heat seal layer (D).

Claims

[1] A cover film comprising at least, in order, a substrate layer (A), an intermediate layer (B), a peel layer (C) and a heat seal layer (D), wherein

the peel layer (C) comprises a resin composition comprising a styrenic resin composition (a) having a styrene-diene block copolymer as a main component, and an ethylene-α-olefin random copolymer (b), the ethylene-α-olefin random copolymer occupying 20 to 50 mass% of the peel layer, and the resin composition having a Vicat softening temperature of 55 to 80 °C; and

the heat seal layer (D) comprises an acrylic resin with a glass transition temperature of 55 to 80 °C.

[2] The cover film according to claim 1, wherein the Vicat softening temperature of the resin composition comprised in the peel layer (C) is 60 to 75 °C.

[3] The cover film according to claim 1 or 2, wherein the thickness of the substrate layer (A) after drying is 12 to 20 μm, the thickness of the intermediate layer (B) after drying is 10 to 40 μm, the thickness of the peel layer (C) after drying is 5 to 20 μm, and the total thickness of the cover film after drying is 45 to 65 μm.

[4] The cover film according to any one of claims 1 to 3, wherein the heat seal layer (D) comprises 100 to 700 parts by mass of conductive microparticles of one of tin oxide, zinc oxide and zinc antimonate having a mass-average particle size of 1.0 μm or less, with respect to 100 parts by mass of the resin constituting the heat seal layer (D).

[5] The cover film according to any one of claims 1 to 4, wherein the heat seal layer (D) comprises 40 to 100 parts by mass of a cationic polymer-type anti-static agent having a quaternary ammonium salt on a side chain, with respect to 100 parts by mass of the resin constituting the heat seal layer (D).